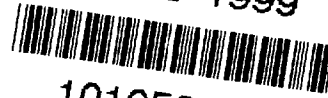


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1. Name of conveying party(ies):

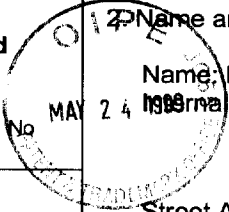
(1) Hideki Hashimoto, (2) Takashi Harada and (3) Keisuke Fujioka

Name and address of receiving party(ies)

Name: Exedy Corporation

Address:

Additional name(s) of conveying party(ies) attached? Yes No



3. Nature of conveyance:

- Assignment, Merger, Security Agreement, Change of Name, Other

Execution Date: 04/14/99 & 04/16/99

Street Address: 1-1, Kidamotomiya 1-chome Neyagawa-shi

City: Osaka, Country: Japan Zip: 572-8570

Additional name(s) & address(es) attached? Yes No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

09/291,966, filed 04/15/99.

B. Patent No.(s)

Additional Application numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Shinjyu Global IP Counselors, LLP Internal Address:

Street Address: 1233 Twentieth Street, NW Suite 700 City: Washington State: D.C. ZIP: 20036

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41) ...\$40.00

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9. Statement and signature.

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5/20/99

Date

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Washington, D.C. 20231

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ASSIGNMENT

[Executed in Japan]

WHEREAS, Hideki HASHIMOTO, a citizen of Japan residing at
19-11-2, Kouzu 1-chome, Katano-shi, Osaka 576,

Takashi HARADA, a citizen of Japan residing at
12-2-225, Mita-cho, Shijonawate-shi, Osaka 575-0033,

Keisuke FUJIOKA, a citizen of Japan residing at
12-2-410, Mita-cho, Shijonawate-shi, Osaka 575-0033,

hereinafter referred to as the Assignor(s), have invented certain new and useful improvements in
A DAMPENING DISK ASSEMBLY

for which the Assignor(s) have executed an Application for United States Letters Patent on even date herewith,

AND WHEREAS, EXEDY Corporation having its principal place
of business at 1-1, Kidamotomiya 1-chome, Neyagawa-shi, Osaka 572-8570, Japan

(hereinafter referred to as the Assignee), is desirous of acquiring the entire right, title, and interest in and to said invention and said Application and in and to any Letters Patent or Patents, United States or foreign as indicated below, to be obtained therefor and thereon:

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is herewith acknowledged, the Assignor(s) sell, assign, and transfer, unto the Assignee, its successors, legal representatives and assigns, the entire right, title, and interest in the United States of America, and in all foreign countries including, but not limited to, the following countries,

Germany

in, to and under said improvements, and said Application, and all original, divisional, renewal, continuation, substitute, or reissue applications thereof, including the right to sue and recover for any past infringement, and all rights of priority from the filing of said Application; and the Assignor(s) hereby authorize and request the Commissioner of Patents and Trademarks to issue all Letters Patent on said improvements or resulting therefrom to said Assignee herein, as assignee of the entire interest therein, for the sole use and behoof of said Assignee, its successors, and assigns, to the full end of the term or terms for which Letters Patent or Patents may be granted.

Further, the Assignor(s) and their legal representatives, heirs, and assigns do hereby agree and covenant without further remuneration that they will communicate to said Assignee, its successors, legal representatives and assigns, any facts known to them respecting said improvements whenever requested, and will testify in any interferences or other legal proceeding in which any of said applications or Letters Patent may become involved, sign all lawful papers, execute and deliver all divisional, continuing, reissue and other applications for Letters Patent on said improvements and all assignments thereof to said Assignee or its legal representatives, successors, or assigns, make all rightful oaths and generally do everything necessary to assist said Assignee, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in the U.S. and said countries, the expenses incident to said applications to be borne and paid by said assignee.

IN TESTIMONY WHEREOF, the undersigned Assignor(s) have affixed their signatures.

This 16th day of April, 19 99 Signature Hideki Hashimoto

This 14th day of April, 19 99 Signature Takashi Harada

This 14th day of April, 19 99 Signature Keisuke Fujioka

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